

深圳康比电子有限公司

KANGBI TECHNOLOGY INDUSTRY CO., LTD.

# 产品规格书

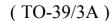
SAMPLE APPROVAL SHEET

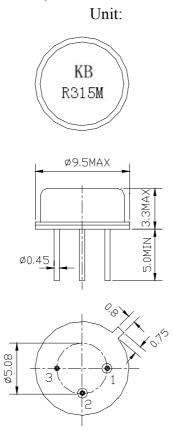
Customer's Approval Certificate Please return this copy as a certification of Y our approval

Checked & Approval by:

Date:







Pin No. Function

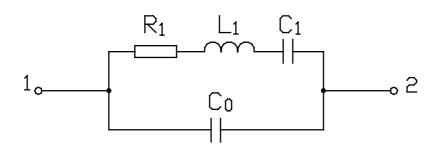
- 1. Input
- 2. Output
- 3. Ground

## 2. Marking

KΒ

R315.00

- 1. Color: Black or Blue
- 2. DR: Manufacture's logo
- 3. 1: One-port SAW Resonator
- 4. 315.00: Center Frequency (MHz)
- 3. Equivalent LC Model



mm

## 4. Performance

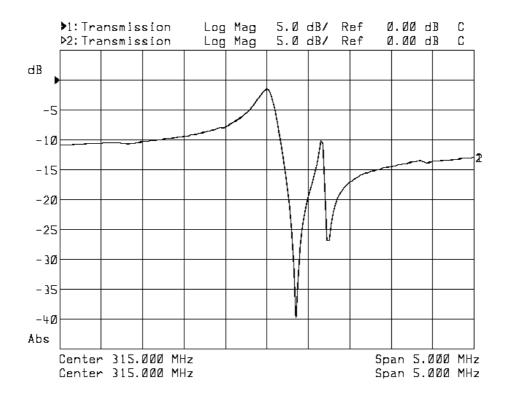
### 4.1 Maximum Rating

DC Voltage V <sub>DC</sub>	10V		
AC Voltage V <sub>PP</sub>	10V (50Hz/60Hz)		
Operation Temperature	-40 °C to +85°C		
Storage Temperature	-45 °C to +85°C		
RF Power Dissipation	0dBm		

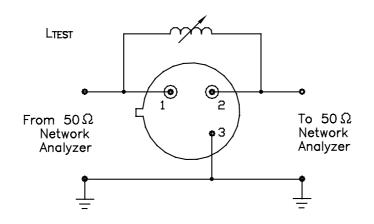
#### 4.2 Electronic Characteristics

Item		Units	Minimum	Typical	Maximum
Center Frequency		MHz	314.925	315	315.075
Insertion Loss		dB	—	1.3	2.5
Quality Factor	Unloaded Q		—	12,000	—
	50 <sup>Ω</sup> Loaded Q		—	1,900	—
Temperature	Turnover Temperature	°C	10	25	40
Stability	Turnover Frequency	KHz	—	fo	—
	Freq. Temp. Coefficient	ppm/°C <sup>2</sup>	—	0.037	—
Frequency Aging		ppm/yr	—	<±10	—
DC Insulation Resistance		MΩ	1.0	_	—
	Motional Resistance R <sub>1</sub>	Ω	_	23	29
RF Equivalent	Motional Inductance L <sub>1</sub>	μH	—	115.2	—
RLC Model	Motional Capacitance C <sub>1</sub>	fF	_	2.2	—
	Shunt Static Capacitance Co	pF	2.1	2.4	2.7

<sup>4.3</sup> Frequency Characteristics



4.4 Test Circuit



Note: Reference temperature shall be  $25\pm2^{\circ}$ °C. However, the measurement may be carried out at 5°C to 35°C unless there is a dispute.

#### 5. Reliability

5.1 Mechanical Shock: The components shall remain within the electrical specifications after 1000 shocks, acceleration  $392 \text{ m/s}^2$ , duration 6 milliseconds.

5.2 Vibration Fatigue: The components shall remain within the electrical specifications after loaded vibration at 20 Hz, amplitude 1.5 mm, for 2 hours.

5.3 Terminal Strength: The components shall remain within the electrical specifications after pulled 2 kgs weight for 10 seconds towards an axis of each terminal.

5.4 High Temperature Storage: The components shall remain within the electrical specifications after being kept at the  $85^{\circ}C \pm 2^{\circ}C$  for 48 hours, then kept at room temperature for 2 hours.

5.5 Low Temperature Storage: The components shall remain within the electrical specifications after being kept at the  $-25^{\circ}C \pm 2^{\circ}C$  for 48 hours, then kept at room temperature for 2 hours.

5.6 Temperature Cycle: The components shall remain within the electrical specifications after 5 cycles of high and low temperature testing ( one cycle:  $80^{\circ}$ C for 30 minutes  $25^{\circ}$ C for 5 minutes  $-25^{\circ}$ C for 30 minutes )than kept at room temperature for 2 hours.

5.7 Solder-heat Resistance: The components shall remain within the electrical specifications after dipped in the solder at 260°C for  $10\pm1$  seconds, then kept at room temperature for 2 hours. (Terminal must be dipped leaving 1.5 mm from the case).

5.8 Solder Ability: Solder ability of terminal shall be kept at more than 80% after dipped in the solder flux at  $230^{\circ}C \pm 5^{\circ}C$  for  $5\pm 1$  seconds.

## 6. Remarks

#### 6.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

#### 6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning.

#### 6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.